# KEVET a VAGEO company

# Floating Electrode (FF-CAP), High Voltage with Flexible Termination X7R Dielectric, 500 – 3,000 VDC (Commercial & Automotive Grade)

### **Overview**

KEMET's Floating Electrode High Voltage with Flexible Termination capacitor (FF-CAP) combines two existing KEMET technologies - Floating Electrode and Flexible Termination. The floating electrode component utilizes a a cascading / serial electrode design configured to form multiple capacitors in series within a single monolithic structure. This unique configuration results in enhanced voltage and ESD performance over standard capacitor designs while allowing for a fail-open condition if mechanically damaged (cracked). The flexible termination component utilizes a conductive silver epoxy between the base metal and nickel barrier layers of KEMET's standard termination system in order to establish pliability while maintaining terminal strength, solderability and electrical performance. Both technologies address the primary failure mode of MLCCs-flex cracks, which are typically the result of excessive tensile and shear stresses produced during board flexure and thermal cycling.

Combined with the stability of an X7R dielectric and designed to accommodate all capacitance requirements, these flex-robust devices are RoHS-compliant, offer up to 5 mm of flex-bend capability and exhibits a predictable change in capacitance with respect to time and voltage.

Capacitance change with reference to ambient temperature is limited to ±15% from -55°C to +125°C.

Whether under-hood or in-cabin, these capacitors are designed to provide reliable performance in mission and safety critical automotive circuits. Stricter testing protocol and inspection criteria have been established for automotive grade products in recognition of potentially harsh environmental conditions. KEMET automotive grade series capacitors meet the demanding Automotive Electronics Council's AEC-Q200 qualification requirements.



## **Ordering Information**

C	1210	Υ	154	K	C	R	A	С	TU
Ceramic	Case Size (L" x W")	Specification/ Series	Capacitance Code (pF)	Capacitance Tolerance	Rated Voltage (VDC)	Dielectric	Failure Rate/ Design	Termination Finish <sup>1</sup>	Packaging/ Grade (C-Spec)
	0805 1206 1210 1808 1812 1825 2220 2225	Y = Floating Electrode with Flexible Termination	Two significant digits and number of zeros	J = ±5% K = ±10% M = ±20%	C = 500 B = 630 D = 1,000 F = 1,500 G = 2,000 Z = 2,500 H = 3,000	R = X7R	A = N/A	C = 100% Matte Sn L = SnPb (5% Pb minimum)	See "Packaging C-Spec Ordering Options Table"

<sup>&</sup>lt;sup>1</sup> Additional termination finish options may be available. Contact KEMET for details.

<sup>&</sup>lt;sup>1</sup> SnPb termination finish option is not available on automotive grade product.



## **Packaging C-Spec Ordering Options Table**

Packaging Type	Packaging/Grade Ordering Code (C-Spec)
Commerc	ial Grade <sup>1</sup>
Bulk Bag	Not required (Blank)
7" Reel / Unmarked	TU
13" Reel / Unmarked	7210
7" Reel / Marked	TM
13" Reel / Marked	7215
Automotiv	ve Grade <sup>3</sup>
7" Reel	AUTO
13" Reel / Unmarked	AUT07210

<sup>&</sup>lt;sup>1</sup> Default packaging is "Bulk Bag". An ordering code C-Spec is not required for "Bulk Bag" packaging.

## **Benefits**

- · Floating Electrode/fail open design
- AEC-Q200 automotive qualified
- -55°C to +125°C operating temperature range
- · Industry leading CV values
- · Superior flex performance (up to 5 mm)
- · Exceptional performance at high frequencies
- · Lead (Pb)-Free, RoHS and REACH compliant
- EIA 0805, 1206, 1210, 1808, 1812, 1825, 2220 and 2225 case sizes

- DC voltage ratings of 500 V, 630 V, 1 KV, 1.5 KV, 2 KV, 2.5 KV and 3 KV
- Capacitance offerings ranging from 10 pF to 220 nF
- Available capacitance tolerances of ±5%, ±10% or ±20%
- · Low ESR and ESL
- Non-polar device, minimizing installation concerns
- 100% pure matte tin-plated termination finish allowing for excellent solderability
- SnPb plated termination finish option available upon request (5% Pb minimum)

# **Applications**

- EV/HEV (drive systems, charging)
- · LCD fluorescent backlight ballasts
- Power converters
- LAN/WAN interface
- Voltage multiplier circuits

- · High voltage decoupling
- Filters
- · DC blocking
- ESD Protection

## **Application Note**

X7R dielectric is not recommended for AC line filtering or pulse applications. These capacitors and/or the assembled circuit board containing these capacitors may require a protective surface coating to prevent external surface arcing.

<sup>&</sup>lt;sup>1</sup> The terms "Marked" and "Unmarked" pertain to laser marking option of capacitors. All packaging options labeled as "Unmarked" will contain capacitors that have not been laser marked.

<sup>&</sup>lt;sup>2</sup> The 2 mm pitch option allows for double the packaging quantity of capacitors on a given reel size. This option is limited to EIA 0603 (1608 metric) case size devices. For more information regarding 2 mm pitch option see "Tape & Reel Packaging Information".

<sup>&</sup>lt;sup>3</sup> Reeling tape options (Paper or Plastic) are dependent on capacitor case size (L" x W") and thickness dimension. See "Chip Thickness/Tape & Reel Packaging Quantities" and "Tape & Reel Packaging Information".

<sup>&</sup>lt;sup>3</sup> For additional Information regarding "AUTO" C-Spec options, see "Automotive C-Spec Information".

<sup>3</sup> All Automotive packaging C-Specs listed exclude the option to laser mark components. Please contact KEMET if you require a laser marked option. For more information see "Capacitor Marking".



## **Automotive C-Spec Information**

KEMET automotive grade products meet or exceed the requirements outlined by the Automotive Electronics Council. Details regarding test methods and conditions are referenced in document AEC-Q200, Stress Test Qualification for Passive Components. These products are supported by a Product Change Notification (PCN) and Production Part Approval Process warrant (PPAP).

Automotive products offered through our distribution channel have been assigned an inclusive ordering code C-Spec, "AUTO." This C-Spec was developed in order to better serve small and medium-sized companies that prefer an automotive grade component without the requirement to submit a customer Source Controlled Drawing (SCD) or specification for review by a KEMET engineering specialist. This C-Spec is therefore not intended for use by KEMET OEM automotive customers and are not granted the same "privileges" as other automotive C-Specs. Customer PCN approval and PPAP request levels are limited (see details below.)

#### **Product Change Notification (PCN)**

The KEMET product change notification system is used to communicate primarily the following types of changes:

- Product/process changes that affect product form, fit, function, and/or reliability
- · Changes in manufacturing site
- Product obsolescence

KEMET Automotive	Customer Notifica	tion Due To:	Days Prior To
C-Spec	Process/Product change	Obsolescence*	Implementation
KEMET assigned <sup>1</sup>	Yes (with approval and sign off)	Yes	180 days minimum
AUT0	Yes (without approval)	Yes	90 days minimum

<sup>&</sup>lt;sup>1</sup> KEMET assigned C-Specs require the submittal of a customer SCD or customer specification for review. For additional information contact KEMET.

#### **Production Part Approval Process (PPAP)**

The purpose of the Production Part Approval Process is:

- To ensure that supplier can meet the manufacturability and quality requirements for the purchased parts.
- To provide the evidence that all customer engineering design records and specification requirements are properly understood and fulfilled by the manufacturing organization.
- To demonstrate that the established manufacturing process has the potential to produce the part.

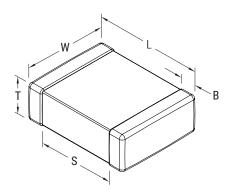
KEMET Automotive			PPAP Level		
C-Spec	1	2	3	4	5
KEMET assigned <sup>1</sup>	•	•	•	•	•
AUT0			0		

<sup>&</sup>lt;sup>1</sup> KEMET assigned C-Specs require the submittal of a customer SCD or customer specification for review. For additional information contact KEMET.

- Part number specific PPAP available with customer information included.
- Product family PPAP only



## **Dimensions - Millimeters (Inches)**



EIA Size Code	Metric Size Code	L Length	W Width	T Thickness	B Bandwidth	S Separation Minimum	Mounting Technique
0805	2012	2.00 (0.079) ±0.30 (0.012)	1.25 (0.049) ± 0.30 (0.012)		0.50 (0.02) ±0.25 (0.010)	0.75 (0.030)	Solder Wave or
1206	3216	3.30 (0.130) ±0.40 (0.016)	1.60 (0.063) ± 0.35(0.013)		0.60 (0.024) ±0.25 (0.010)		Solder Reflow
1210	3225	3.30 (0.130) ±0.40 (0.016)	2.60(0.102) ± 0.30(0.012)		0.60 (0.024) ±0.25 (0.010)		
1808	4520	4.70 (0.185) ±0.50 (0.020)	2.00 (0.079) ± 0.20 (0.008)	See Table 2 for	0.70 (0.028) ±0.35 (0.014)		
1812	4532	4.50 (0.178) ±0.40 (0.016)	3.20 (0.126) ± 0.30 (0.012)	Thickness	0.70 (0.028) ±0.35 (0.014)	N/A	Solder Reflow
1825	4564	4.60 (0.181) ±0.40 (0.016)	6.40 (0.252) ± 0.40 (0.016)		0.70 (0.028) ±0.35 (0.014)		Only
2220	5650	5.90 (0.232) ±0.75 (0.030)	5.00 (0.197) ± 0.40 (0.016)		0.70 (0.028) ±0.35 (0.014)		
2225	5664	5.90 (0.232) ±0.75 (0.030)	6.40 (0.248) ± 0.40 (0.016)		0.70 (0.028) ±0.35 (0.014)		

## **Qualification/Certification**

Commercial Grade products are subject to internal qualification. Details regarding test methods and conditions are referenced in Table 4, Performance & Reliability.

Automotive Grade products meet or exceed the requirements outlined by the Automotive Electronics Council. Details regarding test methods and conditions are referenced in document AEC-Q200, Stress Test Qualification for Passive Components. For additional information regarding the Automotive Electronics Council and AEC-Q200, please visit their website at www.aecouncil.com.

# **Environmental Compliance**

Lead (Pb)-free, RoHS, and REACH compliant without exemptions (excluding SnPb termination finish option).



# Table 1A - Capacitance Range/Selection Waterfall (0805 - 1812 Case Sizes)

		Cas Se	e Si erie		C	080	5Y		C1	120	6 <b>Y</b>			C1	21(	ŊΥ				C1	808	ВҮ					C1	1812	2 <b>Y</b>		
Conscitones	Capacitance	Volta	age C	ode	С	В	D	С	В	D	F	G	С	В	D	F	G	С	В	D	F	G	Z	Н	С	В	D	F	G	Z	Н
Capacitance	Code		d Volt (VDC)	age	200	630	1,000	200	630	1,000	1,500	2,000	200	630	1000	1500	2000	200	630	1000	1500	2000	2500	3000	200	630	1000	1500	2000	2500	3000
			acita eran									F					lity a Chip						ode: ons	S							
10 pF	100	J	K	М	DG	DG	DG	ES	ES	ES	ES	ES	FM	FM	FM		FM		LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
11 pF	110	J	K	М	DG	DG	DG	ES	ES	ES	ES	ES	FM	FM	FM	FM	FM	LB	LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
12 pF	120	J	K	М	DG	DG	DG	ES	ES	ES	ES	ES	FM	FM	FM	FM	FM	LB	LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
13 pF	130	J	K	М	DG	DG	DG	ES	ES	ES	ES	ES	FM	FM	FM	FM	FM		LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
15 pF	150	J	K	М	DG	DG	DG	ES	ES	ES	ES	ES	FM	FM	FM	FM		LB	LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
16 pF	160	J	K	М	DG	DG	DG	ES	ES	ES	ES	ES	FM	FM	FM	FM		LB	LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
18 pF	180	J	K	М	DG	DG	DG	ES	ES	ES	ES	ES	FM	FM	FM	FM		LB	LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
20 pF	200	J	K	M	DG	DG	DG	ES	ES	ES	ES	ES	FM	FM	FM	FM	FM	LB	LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
22 pF	220	J	K	M	DG	DG	DG	ES	ES	ES	ES	ES	FM	FM	FM	FM		LB	LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
24 pF	240	J	K	М	DG	DG	DG	ES	ES	ES	ES	ES	FM	FM	FM	FM	FM	LB	LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
27 pF	270	J	K	M	DG	DG	DG	ES	ES	ES	ES	ES	FM	FM	FM	FM		LB	LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
30 pF	300	J	K	М	DG	DG	DG	ES	ES	ES	ES	ES	FM	FM	FM	FM		LB	LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
33 pF	330	J	K	М	DG	DG	DG	ES	ES	ES	ES	ES	FM	FM	FM	FM	FM	LB	LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
36 pF	360	J	K	M	DG	DG	DG	ES	ES	ES	ES	ES	FM	FM	FM	FM	FM	LB	LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
39 pF	390	J	K	М	DG	DG	DG	ES	ES	ES	ES	ES	FM	FM	FM	FM	FM	LB	LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
43 pF	430	J	K	M	DG	DG	DG	ES	ES	ES	ES	ES	FM	FM	FM	FM	FM	LB	LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
47 pF	470	J	K	M	DG	DG	DG	ES	ES	ES	ES	ES	FM	FM	FM	FM	FM	LB	LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
51 pF	510	J	K	М	DG	DG	DG	ES	ES	ES	ES	ES	FM	FM	FM	FM	FM	LB	LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
56 pF	560	J	K	М	DG	DG	DG	ES	ES	ES	ES	ES	FM	FM	FM	FM	FM	LB	LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
62 pF	620	J	K	М	DG	DG	DG	ES	ES	ES	ES	ES	FM	FM	FM	FM	FM	LB	LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
68 pF	680	J	K	М	DG	DG	DG	ES	ES	ES	ES	ES	FM	FM	FM	FM		LB	LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
75 pF	750	J	K	M	DG	DG	DG	ES	ES	ES	ES	EF	FM	FM	FM	FM	FM	LB	LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
82 pF	820	J	K	М	DG	DG	DG	ES	ES	ES	ES	EF	FM	FM	FM	FM		LB	LB	LB	LB	LB	LB	LB	GB	GB	GB	GB	GB	GB	GB
91 pF	910	J	K	М	DG	DG	DG	ES	ES	ES	ES	EF	FM	FM	FM	FM		LB	LB	LB	LB	LB	LB	LB	GD	GD	GD	GD	GD	GD	GD
100 pF	101	J	K	М	DG	DG	DG	ES	ES	ES	ES	EF	FM	FM	FM	FM	FM	LB	LB	LB	LB	LB	LC	LB	GD	GD	GD	GD	GD	GD	GD
110 pF	111	J	K	М	DG	DG	DG	ES	ES	ES	ES	EU	FM	FM	FM	FM	FM	LB	LB	LB	LB	LB	LC	LB	GD	GD	GD	GD	GD	GD	GD
120 pF	121	J	K	М	DG	DG	DG	ES	ES	ES	ES	EU	FZ	FZ	FZ	FM	FM	LA	LA	LA	LA	LB	LC	LB	GD	GD	GD	GD	GD	GD	GD
130 pF	131	J	K	М	DG	DG	DG	ES	ES	ES	ES	EU	FZ	FZ	FZ	FM	FM	LA	LA	LA	LA	LB	LC	LC	GD	GD	GD	GD	GD	GD	GD
150 pF	151	J	K	М	DG	DG	DG	ES	ES	ES	EF	EU	FZ	FZ	FZ	FM	FM	LA	LA	LA	LA	LB	LC	LC	GK	GK	GK	GK	GK	GK	GK
180 pF	181	J	K	М	DG	DG	DG	ES	ES	ES	EF	EU	FZ	FZ	FZ	FM	FM	LA	LA	LA	LA	LC	LC	LC	GK	GK	GK	GK	GK	GK	GK
	_		d Volt (VDC)	age	200	630	1,000	200	630	1,000	1,500	2,000	200	630	1000	1500	2000	200	630	1000	1500	2000	2500	3000	200	630	1000	1500	2000	2500	3000
Capacitance	Capacitance Code	Volta	С	В	D	С	В	D	F	G	С	В	D	F	G	С	В	D	F	G	Z	Н	С	В	D	F	G	Z	Н		
	0040		se Siz eries		С	0805	ΣY		С	1206	5Y			С	1210	Υ				C.	1808	ЗҮ					С	1812	Y		



# Table 1A - Capacitance Range/Selection Waterfall (0805 - 1812 Case Sizes) cont.

		Cas S	e Si erie		C	080	5Y		C	120	6Y			C1	1210	OY				C1	180	8Y					C1	181:	2Y		
0	Capacitance	Volt	age C	ode	С	В	D	С	В	D	F	G	С	В	D	F	G	С	В	D	F	G	Z	Н	С	В	D	F	G	Z	Н
Capacitance	Code		d Vol (VDC)		200	630	1,000	200	630	1,000	1,500	2,000	200	630	1000	1500	2000	200	630	1000	1500	2000	2500	3000	200	630	1000	1500	2000	2500	3000
			acita Ieran										Sec	Tal						Thic ess l				s							
220 pF	221	J	K	М	DG	DG	DG		ES	ES	EU	EU	FZ	FZ	FZ	FM	FM	LA	LA	LA	LA	LC	LC	LB	GB	GB	GB	GB	GB	GD	GE
270 pF	271	J	K	М	DG	DG	DG	ES	ES	ES	EU	EU	FZ	FZ	FZ	FK	FK	LA	LA	LA	LB	LC	LC	LC	GB	GB	GB	GB	GB	GH	GH
330 pF	331	J	K	M	DG	DG	DG	ES	ES	EF	EU	EU	FZ	FZ	FZ	FK	FK	LA	LA	LA	LB	LC	LC	LC	GB	GB	GB	GB	GB	GH	GH
390 pF	391	J	K	M	DG	DG	DG	ES	ES	EF	EU	EU	FZ	FZ	FZ	FK	FS	LA	LA	LA	LB	LA	LC	LC	GB	GB	GB	GB	GD	GK	GH
470 pF	471	J	K	M	DG	DG	DG	ES	ES	EU	EU	EU	FM	FM	FM	FS	FS	LB	LB	LB	LC	LA	LB	LC	GB	GB	GB	GB	GD	GK	GK
560 pF	561	J	K	М	DG	DG	DG	ES	ES	EU	EU	EU	FM	FM	FM	FS	FS	LB	LB	LB	LC	LB	LB	LC	GB	GB	GB	GD	GH	GH	GK
680 pF	681	J	K	М	DG	DG	DG	EU	EU	EU	EU	EU	FM	FM	FM	FS	FS	LB	LB	LB	LA	LC	LC	LC	GB	GB	GB	GD	GH	GH	GK
820 pF	821	J	K	M	DG	DG	DG	EU	EU	EU	EU	EU	FM	FM	FM	FS	FL	LB	LB	LB	LB	LB	LC	LC	GB	GB	GB	GD	GH	GH	GK
1,000 pF	102	J	K	M	DG	DG	DG	EU	EU	EU	EU	EU	FM	FM	FM	FS	FL	LB	LB	LB	LB	LB	LC	LC	GB	GB	GB	GH	GK	GK	GK
1,200 pF	122	J	K	М	DG	DG	DG	ES	ES	ES	EU	EU	FK	FK	FK	FS	FM	LC	LC	LC	LC	LC	LA		GB	GB	GB	GH	GK	GK	GK
1,500 pF	152	J	K	M	DG	DG	DG	ES	ES	ES	EU	EU	FS	FS	FS	FL	FM	LC	LC	LC	LC	LC	LC		GB	GB	GB	GH	GK	GK	
1,800 pF	182	J	K	М	DG	DG	DG	EF	EF	EF	EU	EU	FS	FS	FS	FL	FM	LC	LC	LC	LB	LC	LC		GD	GD	GD	GH	GK	GK	
2,200 pF	222	J	K	М	DG	DG	DG	EF	EF	EF	EU	EU	FS	FS	FS	FL	FM	LB	LB	LB	LB	LC	LC		GH	GH	GH	GH	GK	GK	
2,700 pF	272	J	K	М	DG	DG	DG	EF	EF	EF	EU		FS	FS	FS	FL	FM	LC	LC	LC	LB	LC			GB	GB	GB	GH	GM	GM	
3,300 pF	332	J	K	М	DG	DG	DG	EF	EF	EF	EU		FL	FL	FL	FL	FS	LA	LB	LB	LB	LA			GB	GB	GB	GH	GM	GM	
3,900 pF	392	J	K	М	DG			EF	EF	EF	EU		FL	FL	FL	FL	FS	LA	LB	LB	LB	LB			GB	GB	GB	GH	GM	GO	
4,700 pF	472	J	K	М	DG			EF	EF	EF	EU		FL	FL	FL	FL	FS	LA	LB	LB	LB	LC			GH	GH	GH	GH	GH	GO	
5,600 pF	562	J	K	М	DG			EF	EF	EF	EU		F0	FL	FL	FM	FS	LA	LB	LB	LC				GH	GH	GH	GK	GK		
6,800 pF	682	J	K	М	DG			EF	EF	EF	EU		F0	FL	FL	FM	FS	LA	LB	LB	LC				GH	GH	GH	GK	GM		
8,200 pF	822	J	K	М	DG			EU	EU	EU	EU		F0	FL	FL	FK		LA	LC	LC	LC				GH	GH	GH	GK	GM		
10,000 pF	103	J	K	М				EU	EU	EU	EU		FO	FL	FL	FK		LA	LC	LC	LC				GH	GH	GH	GK	GO		
12,000 pF	123	J	K	М	İ			EU					FO	FL	FL	FS		LA	LC	LC	LC				GB	GK	GK	GK			
15,000 pF	153	J	K	М	İ			EU					FO	FU	FU	FL		LA	LC	LC	LC				GB	GK	GK	GK			
18,000 pF	183	J	K	М	İ			İ					FO	FL	FL	FM		LA							GB	GM	GM	GM			
22,000 pF	223	J	K	М	İ			İ					FU	FK	FK	FM		LA							GB	GL	GL	GM			
27,000 pF	273	J	K	М									FM	FK	FK	FK		LB							GH	GO	GO	GO			
33,000 pF	333	J	K	М	l			l					FK	FS	FS	FS		LC							GH	GO	GO	GO			
39,000 pF	393	J	K	М	1			l					FK	FS	FS	FS		LC							GH						
47,000 pF	473	J	K	М	l			l					FS					LC							GH						
56,000 pF	563	J	K	М	l			İ					l					LC							GK						
	_		d Vol	tage	200	630	1,000	500	630	1,000	1,500	2,000	500	630	1000	1500	2000	500	630	1000	1500	2000	2500	3000	500	630	1000	1500	2000	2500	3000
Capacitance	Capacitance Code	<b>—</b>	Voltage Code			В	D	С	В	D	F	G	С	В	D	F	G	С	В	D	F	G	Z	Н	С	В	D	F	G	Z	Н
·	Code		se Siz		С	080	5Y		C	120	6Y			С	1210	Υ		C   B   D   F   G   Z   F							C	1812	<u>'</u> Υ				



# Table 1B - Capacitance Range/Selection Waterfall (1825 - 2225 Case Sizes)

			se Si Serie				C	1825	Υ					С	2220	ŊΥ					C	2225	5Y		
	Cap		tage C		С	В	D	F	G	Z	Н	С	В	D	F	G	Z	Н	С	В	D	F	G	z	Н
Capacitance	Code		ed Vol		200	930	1,000	1,500	2,000	2,500	00(	20	930	000'1	1,500	2,000	92,	9	92	930	1,000	1,500	2,000	2,500	3,000
			(VDC)		25	3	5	7,	2,0	2,5	ຕົ						7	ຕົ			5	7,	2,0	2,5	3,0
			acita Ieran												and Cl ip Thic										
100 pF	101	J	K	М	HG	HG	HG	HG	HG	HG	HG	JK	JK	JK	JK	JK	JK	JK	KF						
110 pF	111	J	K	М	HG	HG	HG	HG	HG	HG	HG	JK	JK	JK	JK	JK	JK	JK	KF						
120 pF	121	J	K	М	HG	HG	HG	HG	HG	HG	HG	JK	JK	JK	JK	JK	JK	JK	KF						
130 pF	131	J	K	M	HG	HG	HG	HG	HG	HG	HG	JK	JK	JK	JK	JK	JK	JK	KF						
150 pF	151	J	K	M	HG	HG	HG	HG	HG	HG	HG	JK	JK	JK	JK	JK	JK	JK	KF						
180 pF	181	J	K	M	HG	HG	HG	HG	HG	HG	HG	JK	JK	JK	JK	JK	JK	JK	KF						
220 pF	221	J	K	M	HE	HE	HE	HE	HE	HE	HG	JK	JK	JK	JK	JK	JK	JK	KF						
270 pF	271	J	K	M	HE	HE	HE	HE	HE	HE	HG	JK	JK	JK	JK	JK	JK	JK	KE	KE	KE	KE	KE	KE	KF
330 pF 390 pF	331 391	J J	K K	M M	HE HE	HE HE	HE HE	HE HE	HE HE	HE	HG HG	JE JE	JE JE	JE JE	JE JE	JE JE	JK JK	JK JK	KE KE	KE KE	KE KE	KE KE	KE KE	KE KE	KF KF
390 pF 470 pF	471	J	K	M	HE	HG	HG	HG	HG	HG	HG	JE	JE	JE	JE	JE	JK	JK	KE	KE	KE	KE	KE	KE	KF
470 pF 560 pF	561	J	K	M	HG	HG	HG	HG	HG	HG	HG	JE	JE	JE	JE	JE	JK	JK	KF	KF	KF	KF	KE	KE	KF
680 pF	681	J	K	M	HG	HG	HG	HG	HG	HG	HG	JE	JE	JE	JK	JK	JK	JK	KF	KF	KF	KF	KE	KF	KF
820 pF	821	J	K	M	HG	HG	HG	HG	HG	HG	HG	JE	JE	JE	JK	JK	JK	JK	KE	KE	KE	KF	KE	KF	KF
1,000 pF	102	J	K	M	HG	HG	HG	HG	HG	HG	HG	JK	JK	JK	JK	JK	JK	JK	KE	KE	KE	KF	KE	KF	KF
1,200 pF	122	J	K	M	HG	HG	HG	HG	HG	HG	HG	JK	JK	JK	JK	JK	JK	JK	KE	KE	KE	KF	KF	KF	KF
1,500 pF	152	J	K	M	HG	HG	HG	HG	HG	HG	HG	JK	JK	JK	JK	JK	JK	JK	KE	KE	KE	KF	KF	KF	KF
1,800 pF	182	J	K	M	HE	HE	HE	HE	HE	HG	HG	JK	JK	JK	JK	JK	JK	JK	KE	KE	KE	KF	KF	KF	KF
2,200 pF	222	J	K	М	HE	HE	HE	HE	HE	HG	HJ	JK	JK	JK	JE	JK	JL	JL	KE	KE	KE	KF	KF	KF	KF
2,700 pF	272	Ĵ	K	М	HE	HE	HE	HE	HE	HG		JK	JK	JK	JE	JK	JL	JL	KE	KE	KE	KE	KE	KF	KF
3,300 pF	332	J	K	М	HE	HE	HE	HE	HE	HG		JK	JK	JK	JE	JK	JE	JE	KE	KE	KE	KE	KE	KF	KF
3,900 pF	392	J	K	М	HE	HE	HE	HE	HE	HG		JK	JK	JK	JE	JK	JE	JE	KF	KF	KF	KE	KE	KF	KF
4,700 pF	472	J	K	М	HE	HE	HE	HE	HG	HG		JK	JK	JK	JE	JK	JK	JK	KF	KF	KF	KE	KE	KF	KF
5,600 pF	562	J	K	М	HE	HE	HE	HE	HJ	HJ		JK	JK	JK	JE	JK	JK	JK	KF	KF	KF	KE	KE	KE	KE
6,800 pF	682	J	K	М	HE	HE	HE	HE	HJ	HJ		JE	JE	JE	JE	JK	JK	JK	KF	KF	KF	KE	KF	KE	KE
8,200 pF	822	J	K	М	HE	HE	HE	HE	HG	HJ		JE	JE	JE	JE	JK	JK	JK	KE	KE	KE	KE	KF	KF	KF
10,000 pF	103	J	K	M	HE	HE	HE	HE	HJ	HK		JE	JE	JE	JE	JL	JL	JL	KE	KE	KE	KE	KH	KH	KH
12,000 pF	123	J	K	M	HE	HE	HE	HG	HJ			JE	JK	JK	JK	JL	JL	JL	KE	KE	KE	KE	KH	KJ	KJ
15,000 pF	153	J	K	M	HE	HE	HE	HG	HK			JE	JK	JK	JK	JL	JN	JN	KE	KE	KE	KE	KH	KJ	KJ
18,000 pF	183	J	K	М	HE	HE	HE	HG				JE	JK	JK	JK	JN			KE	KE	KE	KE	KJ		
22,000 pF	223	J	K	M	HE	HG	HG	HG				JE	JK	JK	JK	JN			KE	KF	KF	KF	KJ		
27,000 pF	273	J	K	М	HE	HG	HG	HG				JE	JK	JK	JK				KE	KF	KF	KF	KJ		
33,000 pF	333	J	K	M	HE	HG	HG	HE				JE	JK	JK	JK				KE	KF	KF	KF			
39,000 pF	393	J	K	M	HE	HG	HG	HG				JE	JK	JK	JK				KE	KF	KF	KF			
47,000 pF	473	J	K	M	HE	HJ	HJ	HJ				JE	JG	JG	JG				KE	KF	KF	KH			
56,000 pF	563	J	K K	M	HE	HG	HG HJ	HJ				JE JE	JE	JE JK	JL				KE	KH	KH	KH			
68,000 pF 82,000 pF	683 823	J J	K	M	HG HG	HJ HJ	нJ	HK				JE	JK JL	JL	JN JN				KE KE	KH KF	KH KF	KJ KJ			
82,000 pF 0.10 μF	104	J	K	M	HG	HK	HK					JE	JN	JN	JIN				KE	KH	KH	KJ			
0.10 μF 0.12 μF	104	J	K	M	HG	III	III					JE	JN	JN					KE	КЛ	KJ	ΝJ			
0.12 μF	154	J	K	M	HG							JK	JIN	JIN					KF	KJ	KJ				
0.13 μF	184	J	K	M	HG							JK							KF	1.0	1.0				
0.22 μF	224	J	K	M	HG							"							KF						
			Rated Voltage (VDC)			630	1,000	1,500	2,000	2,500	3,000	200	630	1,000	1,500	2,000	2,500	3,000	200	630	1,000	1,500	2,000	2,500	3,000
Capacitance	Cap Code		tage C		С	В	D	F	G	Z	Н	С	В	D	F	G	Z	Н	С	В	D	F	G	Z	Н
-		Ca	se Si: Serie:	ze/				1825	Y					(	2220	Y					C	2225	Y		l.



## Table 2A - Chip Thickness/Tape & Reel Packaging Quantities

			Daner O	uontitu1	Diagtic	Duantity.
Thickness	Case	Thickness ±		uantity <sup>1</sup>	Plastic	Quantity
Code	Size <sup>1</sup>	Range (mm)	7" Reel	13" Reel	7" Reel	13" Reel
DG	0805	1.25 ± 0.15	0	0	2,500	10,000
ES	1206	1.00 ± 0.20	0	0	2,500	10,000
EF	1206	1.20 ± 0.15	0	0	2,500	10,000
EU	1206	1.60 ± 0.25	0	0	2,000	8,000
FZ	1210	1.25 ± 0.20	0	0	2,500	10,000
FL	1210	1.40 ± 0.15	0	0	2,000	8,000
F0	1210	1.50 ± 0.20	0	0	2,000	8,000
FU	1210	1.55 ± 0.20	0	0	2,000	8,000
FM	1210	1.70 ± 0.20	0	0	2,000	8,000
FK	1210	2.10 ± 0.20	0	0	2,000	8,000
FS	1210	2.50 ± 0.30	0	0	1,000	4,000
LA	1808	1.40 ± 0.15	0	0	1,000	4,000
LB	1808	1.60 ± 0.15	0	0	1,000	4,000
LC	1808	2.00 ± 0.15	0	0	1,000	4,000
GB	1812	1.00 ± 0.10	0	0	1,000	4,000
GD	1812	1.25 ± 0.15	0	0	1,000	4,000
GE	1812	1.30 ± 0.10	0	0	1,000	4,000
GH	1812	1.40 ± 0.15	0	0	1,000	4,000
GK	1812	1.60 ± 0.20	0	0	1,000	4,000
GL	1812	1.90 ± 0.20	0	0	500	2,000
GM	1812	2.00 ± 0.20	0	0	500	2,000
GO	1812	2.50 ± 0.20	0	0	500	2,000
HE	1825	1.40 ± 0.15	0	0	1,000	4,000
HG	1825	1.60 ± 0.20	0	0	1,000	4,000
HJ	1825	2.00 ± 0.20	0	0	500	2,000
HK	1825	2.50 ± 0.20	0	0	500	2,000
JE	2220	1.40 ± 0.15	0	0	1,000	4,000
JK	2220	1.60 ± 0.20	0	0	1,000	4,000
JG	2220	1.70 ± 0.15	0	0	1,000	4,000
JL	2220	2.00 ± 0.20	0	0	500	2,000
JN	2220	2.50 ± 0.20	0	0	500	2,000
KE	2225	1.40 ± 0.15	0	0	1,000	4,000
KF	2225	1.60 ± 0.20	0	0	1,000	4,000
KH	2225	2.00 ± 0.20	0	0	500	2,000
KJ	2225	2.50 ± 0.20	0	0	500	2,000
Thickness	Case	Thickness ±	7" Reel	13" Reel	7" Reel	13" Reel
Code	Size <sup>1</sup>	Range (mm)	Paper Q	uantity <sup>1</sup>	Plastic (	Quantity

Package quantity based on finished chip thickness specifications.

<sup>&</sup>lt;sup>1</sup> If ordering using the 2 mm Tape and Reel pitch option, the packaging quantity outlined in the table above will be doubled. This option is limited to EIA 0603 (1608 metric) case size devices. For more information regarding 2 mm pitch option see "Tape & Reel Packaging Information".



## **Table 2B - Bulk Packaging Quantities**

Dookso	ing Type	Loose P	ackaging
Раскад	jing Type	Bulk Bag	(default)
Packagi	ng C-Spec <sup>1</sup>	N,	/A <sup>2</sup>
Cas	e Size	Packaging Quantities (	pieces/unit packaging)
EIA (in)	Metric (mm)	Minimum	Maximum
0402	1005		
0603	1608		
0805	2012		50,000
1206	3216		
1210	3225	1	
1808	4520	I	
1812	4532		
1825	4564		20,000
2220	5650		
2225	5664		

<sup>&</sup>lt;sup>1</sup> The "Packaging C-Spec" is a 4 to 8 digit code which identifies the packaging type and/or product grade. When ordering, the proper code must be included in the 15th through 22nd character positions of the ordering code. See "Ordering Information" section of this document for further details. Commercial Grade product ordered without a packaging C-Spec will default to our standard "Bulk Bag" packaging. Contact KEMET if you require a bulk bag packaging option for Automotive Grade products.

<sup>&</sup>lt;sup>2</sup> A packaging C-Spec (see note 1 above) is not required for "Bulk Bag" packaging (excluding Anti-Static Bulk Bag and Automotive Grade products). The 15th through 22nd character positions of the ordering code should be left blank. All product ordered without a packaging C-Spec will default to our standard "Bulk Bag" packaging.



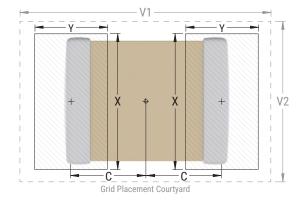
Table 3 - Chip Capacitor Land Pattern Design Recommendations per IPC-7351

EIA Size Code	ze Size Land Protrusion (mm)							Media	sity Lev an (Nor rotrusio		)		Mini	sity Lev mum (L rotrusio	east)	)
Ooue	Code	С	Y	X	V1	V2	С	Y	X	V1	V2	С	Υ	X	V1	V2
0805	2012	0.99	1.44	1.66	4.47	2.71	0.89	1.24	1.56	3.57	2.11	0.79	1.04	1.46	2.42	1.81
1206	3216	1.59	1.62	2.06	5.85	3.06	1.49	1.42	1.96	4.95	2.46	1.39	1.22	1.86	4.25	2.16
1210	3225	1.59	1.62	3.01	5.90	4.01	1.49	1.42	2.91	4.95	3.41	1.39	1.22	2.81	4.25	3.11
1808	4520	2.30	1.75	2.30	7.40	3.30	2.20	1.55	2.20	6.50	2.70	2.10	1.35	2.10	5.80	2.40
1812	4532	2.10	1.80	3.60	7.00	4.60	2.00	1.60	3.50	6.10	4.00	1.90	1.40	3.40	5.40	3.70
1825	4564	2.15	1.80	6.90	7.10	7.90	2.05	1.60	6.80	6.20	7.30	1.95	1.40	6.70	5.50	7.00
2220	5650	2.85	2.10	5.50	8.80	6.50	2.75	1.90	5.40	7.90	5.90	2.65	1.70	5.30	7.20	5.60
2225	5664	2.85	2.10	6.90	8.80	7.90	2.75	1.90	6.80	7.90	7.30	2.65	1.70	6.70	7.20	7.00

**Density Level A:** For low-density product applications. Recommended for wave solder applications and provides a wider process window for reflow solder processes. KEMET only recommends wave soldering of EIA 0603, 0805 and 1206 case sizes.

**Density Level B:** For products with a moderate level of component density. Provides a robust solder attachment condition for reflow solder processes. **Density Level C:** For high component density product applications. Before adapting the minimum land pattern variations the user should perform qualification testing based on the conditions outlined in IPC Standard 7351 (IPC-7351).

Image below based on Density Level B for an EIA 1210 case size.





# **Soldering Process**

#### **Recommended Soldering Technique:**

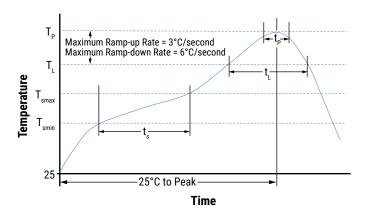
- Solder wave or solder reflow for EIA case sizes 0603, 0805 and 1206
- · All other EIA case sizes are limited to solder reflow only

#### **Recommended Reflow Soldering Profile:**

KEMET's families of surface mount multilayer ceramic capacitors (SMD MLCCs) are compatible with wave (single or dual), convection, IR or vapor phase reflow techniques. Preheating of these components is recommended to avoid extreme thermal stress. KEMET's recommended profile conditions for convection and IR reflow reflect the profile conditions of the IPC/ J-STD-020 standard for moisture sensitivity testing. These devices can safely withstand a maximum of three reflow passes at these conditions.

Profile Feature	Terminati	ion Finish
1 Tome Teature	SnPb	100% Matte Sn
Preheat/Soak		
Temperature Minimum (T <sub>Smin</sub> )	100°C	150°C
Temperature Maximum (T <sub>Smax</sub> )	150°C	200°C
Time ( $t_s$ ) from $T_{smin}$ to $T_{smax}$	60 - 120 seconds	60 - 120 seconds
Ramp-Up Rate (T <sub>L</sub> to T <sub>P</sub> )	3°C/second maximum	3°C/second maximum
Liquidous Temperature $(T_L)$	183°C	217°C
Time Above Liquidous (t <sub>L</sub> )	60 - 150 seconds	60 - 150 seconds
Peak Temperature (T <sub>P</sub> )	235°C	260°C
Time Within 5°C of Maximum Peak Temperature (t <sub>p</sub> )	20 seconds maximum	30 seconds maximum
Ramp-Down Rate $(T_p \text{ to } T_L)$	6°C/second maximum	6°C/second maximum
Time 25°C to Peak Temperature	6 minutes maximum	8 minutes maximum

Note 1: All temperatures refer to the center of the package, measured on the capacitor body surface that is facing up during assembly reflow.





# Table 4 - Performance & Reliability: Test Methods and Conditions

Stress	Reference	Test Condition	Limits
Visual and Mechanical	KEMET Internal	No defects that may affect performance (10X)	Dimensions according KEMET Spec Sheet
Capacitance (Cap)	KEMET Internal	C ≤ 10 μF 1 kHz ±50 Hz and 1.0 ±0.2 V <sub>rms</sub> or 0.5 ±0.2 V <sub>rms</sub> * C > 10 μF120 Hz ±10 Hz and 0.5 ±0.1 V <sub>rms</sub> are voltage  * See part number specification sheet for voltage  Capacitance measurements (including tolerance) are indexed to a referee time of 48 or 1,000 hours  Please refer to a part number specification sheet for referee time details	Within Tolerance
Dissipation Factor (DF)	KEMET Internal	C ≤ 10 μF Frequency: 1 kHz ±50 Hz Voltage*:1.0 ±0.2 $V_{rms}$ , 0.5 ±0.2 $V_{rms}$ , C > 10 μF Frequency: 120 Hz ±10 Hz Voltage: 0.5 ±0.1 $V_{rms}$ * See part number specification sheet for voltage	Within Specification Dissipation factor (DF) maximum limit at 25°C = 2.5%
Insulation Resistance (IR)	KEMET Internal	500 VDC applied for 120 ±5 seconds at 25°C	Within Specification To obtain IR limit, divide MΩ-μF value by the capacitance and compare to GΩ limit. Select the lower of the two limits.
Temperature Coefficient of Capacitance (TCC)	KEMET Internal	C ≤ 10 $\mu$ F Frequency: 1 kHz ±50 Hz Voltage*: 1.0 ±0.2 V <sub>rms</sub> , 0.5 ±0.2 V <sub>rms</sub> , 0.2 ±0.1 V <sub>rms</sub> C > 10 $\mu$ F Frequency: 120 Hz ±10 Hz Voltage: 0.5 ±0.1 V <sub>rms</sub> * See part number specification sheet for voltage     Step   Temperature (°C)	Capacitance ±15% over -55°C to +125°C



# Table 4 - Performance & Reliability: Test Methods and Conditions cont.

Stress	Reference	Test Condition	Limits
Dielectric Withstanding Voltage (DWV)	KEMET Internal	150% of rated voltage for voltage rating of < 1,000 V 120% of rated voltage for voltage rating of $\geq$ 1,000 V (5 $\pm$ 1 seconds and charge/discharge not exceeding 50 mA)	Cap: Initial Limit DF: Initial Limit IR: Initial Limit Withstand test voltage without insulation breakdown or damage.
Aging Rate (Maximum % Capacitance Loss/Decade Hour)	KEMET Internal	Capacitance measurements (including tolerance) are indexed to a referee time of 48 or 1,000 hours.  Please refer to a part number specific datasheet for referee time details.	Please refer to a part number specification sheet for specific Aging rate
Terminal Strength	KEMET Internal	Shear stress test per specific case size, Time: 60 ±1 second.  Case Size Force  0805 9N ≥ 1206 18N	No evidence of mechanical damage
Board Flex	AEC-Q200-005	Standard Termination System 2.0 mm Flexible Termination System 3.0 mm Test Time: 60± 5 seconds Ramp Time: 1 mm/second	No evidence of mechanical damage
Solderability	J-STD-002	Condition: 4 hours ±15 minutes at 155°C dry bake apply all methods Test 245 ±5°C (SnPb & Pb-Free)	Visual Inspection. 95% coverage on termination. No leaching
Temperature Cycling	JESD22 Method JA-104	1,000 cycles (-55°C to +125°C) 2 - 3 cycles per hour Soak Time: 1 or 5 minute	Measurement at 24 hours ±4 hours after test conclusion. Cap: Initial Limit DF: Initial Limit IR: Initial Limit
Biased Humidity	MIL-STD-202 Method 103	Load Humidity: 1,000 hours 85°C/85% RH and 200 VDC maximum  Low Volt Humidity: 1,000 hours 85°C/85% RH and 1.5 V.	Measurement at 24 hours ±4 hours after test conclusion. Within Post Environmental Limits Cap: ±20% shift IR: 10% of Initial Limit DF Limit Maximum: 3.0%
Moisture Resistance	MIL-STD-202 Method 106	Number of Cycles Required: 10, 24 hours per cycle. Steps 7a and 7b not required	Measurement at 24 hours ±4 hours after test conclusion. Within Post Environmental Limits Cap: ±20% shift IR: 10% of Initial Limit DF Limit Maximum: 3.0%
Thermal Shock	MIL-STD-202 Method 107	Number of Cycles Required: 5, (-55°C to 125°C) Dwell time 15 minutes.	Cap: Initial Limit DF: Initial Limit IR: Initial Limit



## Table 4 - Performance & Reliability: Test Methods and Conditions cont.

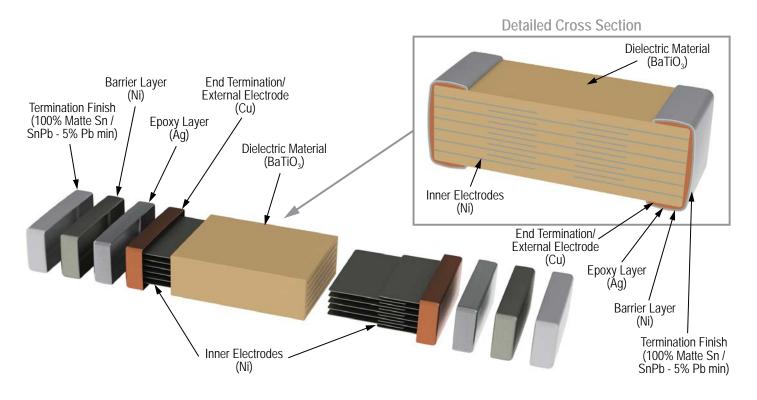
Stress	Reference	Test Condition	Limits
High Temperature Life	MIL-STD-202	1,000 hours at 125°C with 1.2 X rated voltage applied.	Within Post Environmental Limits Cap: ±20% shift IR: 10% of Initial Limit
Storage Life	Method 108	1,000 hours at 150°C, Unpowered	DF Limit Maximum: 3.0%
Vibration	MIL-STD-202 Method 204	5 g's for 20 minutes, 12 cycles each of 3 orientations. Test from 10 – 2,000 Hz	Cap: Initial Limit DF: Initial Limit IR: Initial Limit
Mechanical Shock	MIL-STD-202 Method 213	1,500 g's 0.5 millisecond Half-sine, Velocity Change: 15.4 feet/second (Condition F)	Cap: Initial Limit DF: Initial Limit IR: Initial Limit
Resistance to Solvents	MIL-STD-202 Method 215	Add Aqueous wash chemical OKEMCLEAN (A 6% concentrated Oakite cleaner) or equivalent. Do not use banned solvents.	Visual Inspection 10X Readable marking, no decoloration or stains. No physical damage.

## **Storage and Handling**

Ceramic chip capacitors should be stored in normal working environments. While the chips themselves are quite robust in other environments, solderability will be degraded by exposure to high temperatures, high humidity, corrosive atmospheres, and long term storage. In addition, packaging materials will be degraded by high temperature—reels may soften or warp and tape peel force may increase. KEMET recommends that maximum storage temperature not exceed 40°C and maximum storage humidity not exceed 70% relative humidity. Temperature fluctuations should be minimized to avoid condensation on the parts and atmospheres should be free of chlorine and sulfur bearing compounds. For optimized solderability chip stock should be used promptly, preferably within 1.5 years of receipt.



## Construction





## **Capacitor Marking (Optional)**

These surface mount multilayer ceramic capacitors are normally supplied unmarked. If required, they can be marked as an extra cost option. Marking is available on most KEMET devices, but must be requested using the correct ordering code identifier(s). If this option is requested, two sides of the ceramic body will be laser marked with a "K" to identify KEMET, followed by two characters (per EIA–198 - see table below) to identify the capacitance value. EIA 0603 case size devices are limited to the "K" character only.

Laser marking option is <u>not</u> available on:

- · COG, ultra stable X8R and Y5V dielectric devices.
- EIA 0402 case size devices.
- EIA 0603 case size devices with flexible termination option.
- KPS commercial and automotive grade stacked devices
- X7R dielectric products in capacitance values outlined below.

<b>EIA Case Size</b>	<b>Metric Size Code</b>	Capacitance
0603	1608	≤ 170 pF
0805	2012	≤ 150 pF
1206	3216	≤ 910 pF
1210	3225	≤ 2,000 pF
1808	4520	≤ 3,900 pF
1812	4532	≤ 6,700 pF
1825	4564	≤ 0.018 µF
2220	5650	≤ 0.027 µF
2225	5664	≤ 0.033 µF

Marking appears in legible contrast. Illustrated below is an example of an MLCC with laser marking of "KA8", which designates a KEMET device with rated capacitance of 100  $\mu$ F. Orientation of marking is vendor optional.





# **Capacitor Marking (Optional) cont.**

	Capacitance (pF) For Various Alpha/Numeral Identifiers									
Aluba						Numera	ıl			
Alpha	9	0	1	2	3	4	5	6	7	8
Character					Capa	citance	e (pF)			
Α	0.10	1.0	10	100	1,000	10,000	100,000	1,000,000	10,000,000	100,000,000
В	0.11	1.1	11	110	1,100	11,000	110,000	1,100,000	11,000,000	110,000,000
С	0.12	1.2	12	120	1,200	12,000	120,000	1,200,000	12,000,000	120,000,000
D	0.13	1.3	13	130	1,300	13,000	130,000	1,300,000	13,000,000	130,000,000
E	0.15	1.5	15	150	1,500	15,000	150,000	1,500,000	15,000,000	150,000,000
F	0.16	1.6	16	160	1,600	16,000	160,000	1,600,000	16,000,000	160,000,000
G	0.18	1.8	18	180	1,800	18,000	180,000	1,800,000	18,000,000	180,000,000
Н	0.20	2.0	20	200	2,000	20,000	200,000	2,000,000	20,000,000	200,000,000
J	0.22	2.2	22	220	2,200	22,000	220,000	2,200,000	22,000,000	220,000,000
K	0.24	2.4	24	240	2,400	24,000	240,000	2,400,000	24,000,000	240,000,000
L	0.27	2.7	27	270	2,700	27,000	270,000	2,700,000	27,000,000	270,000,000
М	0.30	3.0	30	300	3,000	30,000	300,000	3,000,000	30,000,000	300,000,000
N	0.33	3.3	33	330	3,300	33,000	330,000	3,300,000	33,000,000	330,000,000
Р	0.36	3.6	36	360	3,600	36,000	360,000	3,600,000	36,000,000	360,000,000
Q	0.39	3.9	39	390	3,900	39,000	390,000	3,900,000	39,000,000	390,000,000
R	0.43	4.3	43	430	4,300	43,000	430,000	4,300,000	43,000,000	430,000,000
S	0.47	4.7	47	470	4,700	47,000	470,000	4,700,000	47,000,000	470,000,000
T	0.51	5.1	51	510	5,100	51,000	510,000	5,100,000	51,000,000	510,000,000
U	0.56	5.6	56	560	5,600	56,000	560,000	5,600,000	56,000,000	560,000,000
V	0.62	6.2	62	620	6,200	62,000	620,000	6,200,000	62,000,000	620,000,000
W	0.68	6.8	68	680	6,800	68,000	680,000	6,800,000	68,000,000	680,000,000
Х	0.75	7.5	75	750	7,500	75,000	750,000	7,500,000	75,000,000	750,000,000
Υ	0.82	8.2	82	820	8,200	82,000	820,000	8,200,000	82,000,000	820,000,000
Z	0.91	9.1	91	910	9,100	91,000	910,000	9,100,000	91,000,000	910,000,000
а	0.25	2.5	25	250	2,500	25,000	250,000	2,500,000	25,000,000	250,000,000
b	0.35	3.5	35	350	3,500	35,000	350,000	3,500,000	35,000,000	350,000,000
d	0.40	4.0	40	400	4,000	40,000	400,000	4,000,000	40,000,000	400,000,000
е	0.45	4.5	45	450	4,500	45,000	450,000	4,500,000	45,000,000	450,000,000
f	0.50	5.0	50	500	5,000	50,000	500,000	5,000,000	50,000,000	500,000,000
m	0.60	6.0	60	600	6,000	60,000	600,000	6,000,000	60,000,000	600,000,000
n	0.70	7.0	70	700	7,000	70,000	700,000	7,000,000	70,000,000	700,000,000
t	0.80	8.0	80	800	8,000	80,000	800,000	8,000,000	80,000,000	800,000,000
у	0.90	9.0	90	900	9,000	90,000	900,000	9,000,000	90,000,000	900,000,000



## **Tape & Reel Packaging Information**

KEMET offers multilayer ceramic chip capacitors packaged in 8, 12 and 16 mm tape on 7" and 13" reels in accordance with EIA Standard 481. This packaging system is compatible with all tape-fed automatic pick and place systems. See Table 2 for details on reeling quantities for commercial chips.

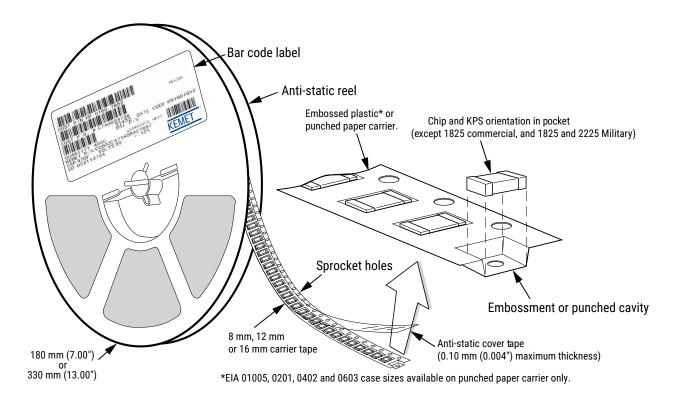


Table 5 - Carrier Tape Configuration, Embossed Plastic & Punched Paper (mm)

	Tape	Embosse	d Plastic	Punche	d Paper
<b>EIA Case Size</b>	Size	7" Reel	13" Reel	7" Reel	13" Reel
	(W)*	Pitch	(P <sub>1</sub> )*	Pitch	(P <sub>1</sub> )*
01005 - 0402	8			2	2
0603	8			2/4	2/4 -
0805	8	4	4	4	4
1206 - 1210	8	4	4	4	4
1805 - 1808	12	4	4		
≥ 1812	12	8	8		
KPS 1210	12	8	8		
KPS 1812 and 2220	16	12	12		
Array 0612	8	4	4		

<sup>\*</sup>Refer to Figures 1 and 2 for W and  $P_1$  carrier tape reference locations.

## New 2 mm Pitch Reel Options\*

	Packaging Ordering Code (C-Spec)	Packaging Type/Options
1	C-3190	Automotive grade 7" reel unmarked
١	C-3191	Automotive grade 13" reel unmarked
	C-7081	Commercial grade 7" reel unmarked
	C-7082	Commercial grade 13" reel unmarked

<sup>\* 2</sup> mm pitch reel only available for 0603 EIA case size. 2 mm pitch reel for 0805 EIA case size under development.

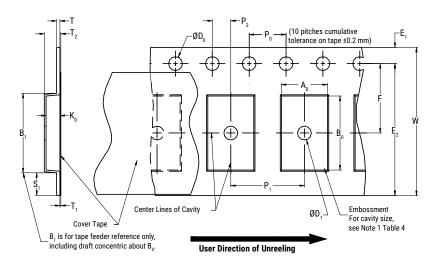
## Benefits of Changing from 4 mm to 2 mm Pitching Spacing

- Lower placement costs.
- Double the parts on each reel results in fewer reel changes and increased efficiency.
- Fewer reels result in lower packaging, shipping and storage costs, reducing waste.

<sup>\*</sup>Refer to Tables 6 and 7 for tolerance specifications.



## Figure 1 - Embossed (Plastic) Carrier Tape Dimensions



## **Table 6 – Embossed (Plastic) Carrier Tape Dimensions**

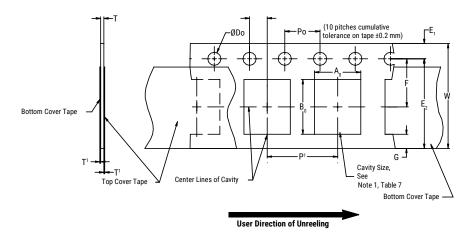
Metric will govern

	Constant Dimensions — Millimeters (Inches)								
Tape Size	D <sub>0</sub>	D <sub>1</sub> Minimum Note 1	E <sub>1</sub>	P <sub>0</sub>	P <sub>2</sub>	R Reference Note 2	S <sub>1</sub> Minimum Note 3	T Maximum	T <sub>1</sub> Maximum
8 mm		1.0 (0.039)				25.0 (0.984)			
12 mm	1.5 +0.10/-0.0 (0.059 +0.004/-0.0)	1.5	1.75 ±0.10 (0.069 ±0.004)	4.0 ±0.10 (0.157 ±0.004)	2.0 ±0.05 (0.079 ±0.002)	30	0.600 (0.024)	0.600 (0.024)	0.100 (0.004)
16 mm		(0.059)				(1.181)			
		1	Variable Dime	ensions — Mil	limeters (Inch	nes)			
Tape Size	Pitch	B <sub>1</sub> Maximum Note 4	E <sub>2</sub> Minimum	F	P <sub>1</sub>	T <sub>2</sub> Maximum	W Maximum	A <sub>0</sub> ,B <sub>0</sub>	& K <sub>0</sub>
8 mm	Single (4 mm)	4.35 (0.171)	6.25 (0.246)	3.5 ±0.05 (0.138 ±0.002)	4.0 ±0.10 (0.157 ±0.004)	2.5 (0.098)	8.3 (0.327)		
12 mm	Single (4 mm) and double (8 mm)	8.2 (0.323)	10.25 (0.404)	5.5 ±0.05 (0.217 ±0.002)	8.0 ±0.10 (0.315 ±0.004)	4.6 (0.181)	12.3 (0.484)	Not	te 5
16 mm	Triple (12 mm)	12.1 (0.476)	14.25 (0.561)	7.5 ±0.05 (0.138 ±0.002)	12.0 ±0.10 (0.157 ±0.004)	4.6 (0.181)	16.3 (0.642)		

- 1. The embossment hole location shall be measured from the sprocket hole controlling the location of the embossment. Dimensions of the embossment location and the hole location shall be applied independently of each other.
- 2. The tape with or without components shall pass around R without damage (see Figure 6.)
- 3. If  $S_1 < 1.0$  mm, there may not be enough area for a cover tape to be properly applied (see EIA Standard 481, paragraph 4.3, section b.)
- 4. B, dimension is a reference dimension for tape feeder clearance only.
- 5. The cavity defined by  $A_{n}$ ,  $B_{n}$  and  $K_{n}$  shall surround the component with sufficient clearance that:
  - (a) the component does not protrude above the top surface of the carrier tape.
  - (b) the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.
  - (c) rotation of the component is limited to 20° maximum for 8 and 12 mm tapes and 10° maximum for 16 mm tapes (see Figure 3.)
  - (d) lateral movement of the component is restricted to 0.5 mm maximum for 8 and 12 mm wide tape and to 1.0 mm maximum for 16 mm tape (see Figure 4.)
  - (e) for KPS product,  $A_0$  and  $B_0$  are measured on a plane 0.3 mm above the bottom of the pocket.
  - (f) see addendum in EIA Standard 481 for standards relating to more precise taping requirements.



# Figure 2 - Punched (Paper) Carrier Tape Dimensions



# Table 7 - Punched (Paper) Carrier Tape Dimensions

Metric will govern

	Constant Dimensions — Millimeters (Inches)							
Tape Size	D <sub>0</sub>	E <sub>1</sub>	P <sub>0</sub>	P <sub>2</sub>	T <sub>1</sub> Maximum	G Minimum	R Reference Note 2	
8 mm	1.5 +0.10 -0.0 (0.059 +0.004 -0.0)	1.75 ±0.10 (0.069 ±0.004)	4.0 ±0.10 (0.157 ±0.004)	2.0 ±0.05 (0.079 ±0.002)	0.10 (0.004) maximum	0.75 (0.030)	25 (0.984)	
	Variable Dimensions — Millimeters (Inches)							
Tape Size	Pitch	E2 Minimum	F	P <sub>1</sub>	T Maximum	W Maximum	$A_0B_0$	
8 mm	Half (2 mm)	6.25	3.5 ±0.05	2.0 ±0.05 (0.079 ±0.002)	1.1	8.3 (0.327)	Note 1	
8 mm	Single (4 mm)	(0.246)	(0.246) (0.138 ±0.002)	4.0 ±0.10 (0.157 ±0.004)	(0.098)	8.3 (0.327)	Note 1	

- 1. The cavity defined by  $A_{o}$ ,  $B_{o}$  and T shall surround the component with sufficient clearance that:
  - a) the component does not protrude beyond either surface of the carrier tape.
  - b) the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.
  - c) rotation of the component is limited to 20° maximum (see Figure 3.)
  - d) lateral movement of the component is restricted to 0.5 mm maximum (see Figure 4.)
  - e) see addendum in EIA Standard 481 for standards relating to more precise taping requirements.
- 2. The tape with or without components shall pass around R without damage (see Figure 6.)



## **Packaging Information Performance Notes**

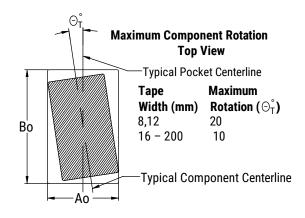
- 1. Cover Tape Break Force: 1.0 kg minimum.
- 2. Cover Tape Peel Strength: The total peel strength of the cover tape from the carrier tape shall be:

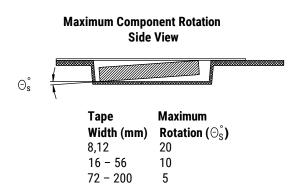
Tape Width	Peel Strength
8 mm	0.1 to 1.0 newton (10 to 100 gf)
12 and 16 mm	0.1 to 1.3 newton (10 to 130 gf)

The direction of the pull shall be opposite the direction of the carrier tape travel. The pull angle of the carrier tape shall be 165° to 180° from the plane of the carrier tape. During peeling, the carrier and/or cover tape shall be pulled at a velocity of 300 ±10 mm/minute.

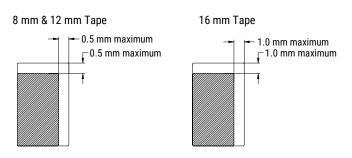
**3. Labeling:** Bar code labeling (standard or custom) shall be on the side of the reel opposite the sprocket holes. *Refer to EIA Standards 556 and 624*.

## **Figure 3 – Maximum Component Rotation**

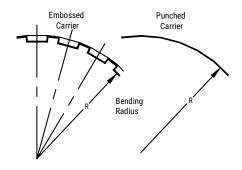




# Figure 4 - Maximum Lateral Movement

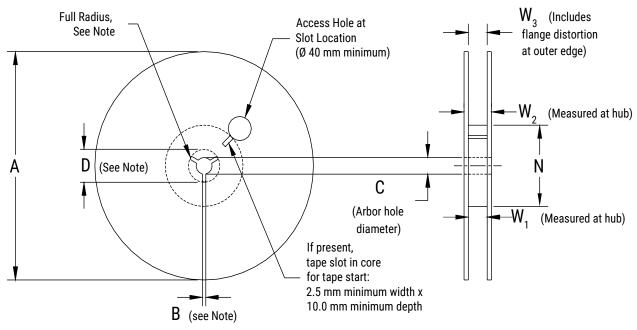


# Figure 5 - Bending Radius





## Figure 6 - Reel Dimensions



Note: Drive spokes optional; if used, dimensions B and D shall apply.

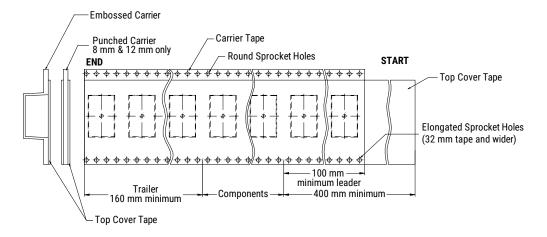
## **Table 8 - Reel Dimensions**

Metric will govern

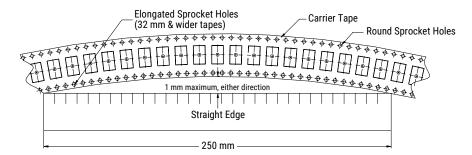
	Constant Dimensions — Millimeters (Inches)						
Tape Size	A	B Minimum	С	D Minimum			
8 mm	178 ±0.20						
12 mm	(7.008 ±0.008) or	1.5 (0.059)	13.0 +0.5/-0.2 (0.521 +0.02/-0.008)	20.2 (0.795)			
16 mm	330 ±0.20 (13.000 ±0.008)	, ,	,	()			
	Variable	Dimensions — Millimeter	rs (Inches)				
Tape Size	N Minimum	W <sub>1</sub>	W <sub>2</sub> Maximum	W <sub>3</sub>			
8 mm		8.4 +1.5/-0.0 (0.331 +0.059/-0.0)	14.4 (0.567)				
12 mm	50 (1.969)	12.4 +2.0/-0.0 (0.488 +0.078/-0.0)	18.4 (0.724)	Shall accommodate tape width without interference			
16 mm		16.4 +2.0/-0.0 (0.646 +0.078/-0.0)	22.4 (0.882)				



## Figure 7 - Tape Leader & Trailer Dimensions



## Figure 8 - Maximum Camber





## **Application Guide**

## **Solder Fluxes and Cleaning**

The use of water-soluble fluxes provides advantages of excellent solderability due to high activation. However, these fluxes contain organic acids that can induce arcing under high DC or AC voltages. Notable problem areas are underneath the MLCC where flux can be trapped between the ceramic material and PCB. It is therefore critical that PCBs are properly cleaned to remove all flux residue to maintain reliability.

## **Coating for High Voltage MLCCs**

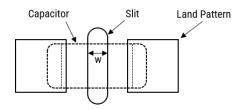
For MLCC ratings ≥1500V, it is recommended to apply a conformal coating to MLCC to prevent surface arcing. To reduce possibility of inducing cracks in the MLCC, select a coating with thermal expansions close to that of the MLCC.

Dielectric	CTE (ppm/°C)
Class II BaTiO₃	10.7
Class I CaZrO₃	9.8

#### Slits in PCB

It is recommended to apply a slit in the PCB under the MLCC to improve washing of flux residue that may get trapped underneath. In some cases, it is not possible to slit entirely through the PCB due to underlying metal planes. It is also acceptable to apply a recessed slit under the MLCC which will also promote cleaning.

- Recommended for case sizes ≥1206
- The width (w) of the slit should be 1mm
- Length of the slit should be as short as possible to prevent damaging the MLCC due to mechanical stress of the PCB.
- Slits also reduce the risk of solder balls under MLCC which decreased the creepage distance.



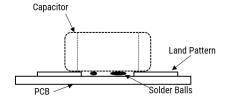
#### **Solder Resist**

If a slit cannot be applied as above, it is recommended to not use solder resist directly under the MLCC. The use of solder resist material reduces the distance between MLCC ceramic material and PCB thus making it difficult to clean.

#### **Solder Balls**

Improper reflow techniques and/or improper washing can induce solder balls under or adjacent to the MLCC. Solder balls reduce the creepage distance between the MLCC terminations and increase the risk of arcing or damage to the ceramic material. To reduce the risk of solder balls:

- Follow KEMET's solder recommendations as outlined in the datasheet.
- If performing a cleaning procedure, properly clean the PCB per KEMET's cleaning recommendations.
- Add slit to the PCB as shown above.





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